

| L Number | Hits | Search Text | DB | Time stamp |
|-------------|------|---|--------------------|---------------------|
| 1 | 63 | (bonding adj wire) and pad and deforming and capillary | USPAT; US-PGPUB | 2003/06/13 14:54 |
| 2 | 45 | ((bonding adj wire) and pad and deforming and capillary) and @ad<=20010322 | USPAT; US-PGPUB | 2003/06/13 14:54 |
| 3 | 546 | (bonding adj wire) and pad and capillary | USPAT; US-PGPUB | 2003/06/13 14:54 |
| 4 | 437 | ((bonding adj wire) and pad and capillary) and @ad<=20010322 | USPAT; US-PGPUB | 2003/06/13 14:54 |
| 5 | 392 | ((bonding adj wire) and pad and capillary) and @ad<=20010322) not ((bonding adj wire) and pad and deforming and capillary) and @ad<=20010322) | USPAT; US-PGPUB | 2003/06/13 14:54 |

review the tagged prior

out after AMN

6/16/03

| | V | 1 Document ID | Issue Date | Pages | Title | Current OR | Current XRef | Retrieval Classif |
|---|--------------------------|---------------|-------------|----------|-------|---|--------------|--|
| | U | [1] | | | | | | |
| 1 | <input type="checkbox"/> | US A1 | 20020100790 | 20020801 | 12 | Bonding tool with polymer coating | 228/4.5 | |
| 2 | <input type="checkbox"/> | US A1 | 20010002726 | 20010607 | 26 | Semiconductor device and method for making the same | 257/678 | |
| 3 | <input type="checkbox"/> | US A1 | 20010000157 | 20010405 | 19 | Semiconductor device and method of making the same | 438/617 | 257/693 |
| 4 | <input type="checkbox"/> | US B1 | 6564449 | 20030520 | 11 | Method of making wire connection in semiconductor device | 29/830 | 29/40; 29/41; 29/46 |
| 5 | <input type="checkbox"/> | US B1 | 6441495 | 20020827 | 26 | Semiconductor device of stacked chips | 257/777 | 257/723; 257/784; 257/786 |
| 6 | <input type="checkbox"/> | US B1 | 6213384 | 20010410 | 10 | Wire bonding method | 228/180.5 | 228/1.1; 228/110.1; 228/4.5; 257/E21.51 |
| 7 | <input type="checkbox"/> | US A | 5994152 | 19991130 | 31 | Fabricating interconnects and tips using sacrificial substrates | 438/617 | 438/117; 438/15 |

| | Inventor | S | C | P | 2 | 3 | 4 | 5 | Image Doc. Displayed | PT |
|---|---------------------------------|-------------------------------------|--------------------------|--------------------------|--------------------------|--------------------------|--------------------------|--------------------------|-------------------------|--------------------------|
| 1 | Sonnenreich, Benjamin et al. | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 2002100790 | <input type="checkbox"/> |
| 2 | Oká, Hiroshi et al. | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 20010002726 | <input type="checkbox"/> |
| 3 | Oká, Hiroshi et al. | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 20010000157 | <input type="checkbox"/> |
| 4 | Tsai, Yu Fang et al. | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 6564449 | <input type="checkbox"/> |
| 5 | Oká, Hiroshi et al. | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 6441495 | <input type="checkbox"/> |
| 6 | Nishiura, Shinichi et al. | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 6213384 | <input type="checkbox"/> |
| 7 | Khandros, Igor Y. et al. | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 5994152 | <input type="checkbox"/> |